**BEST-705** 

:00000 000000:

0.7:0000 / 00.3:0000 / 099:000000

:000000 0000000:

□1 ± 89.5

:0000 00000 00000

 $10 \sim 5$  ° c

N.W:

50G / PC

## 





Name: Solder paste Model: BST-705

Size: \$\phi 35\*20mm Weight: 40g

Composition: SN99/AG0.3/CUO.7 Melting point: 226℃~229℃





Storage:Chilled in refrigerator, the best refrigeration temperature is 5°C~10°C.

Features: 1. When continuous printing, its viscosity changes less, which can obtain very stable printing.

- 2. The circuit with the spacing of 0.4-0.6mm and above can complete fine printing.
- 3. With excellent weld ability, it can show proper viscosity in different parts.
- 4. It is suitable for the return welding furnace of general atmosphere and nitrogen.
- 5. Good weldability can be obtained at extremely high peak temperature.

## PRODUCT PHOTOGRAPH







